

1c979 U.S. PTO
10/052989

11/09/01

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

912

APPL NUM 10052989	FILING DATE 11/09/2001	CLASS 438	SUBCLASS 612	GAU 2812	EXAMINER D. Yu
**APPLICANTS: Hsieh Han-Kun; Wang Shing-Ru; Tung I-Chung; 2818					
**CONTINUING DATA VERIFIED: 11/09/01					
** FOREIGN APPLICATIONS VERIFIED: TAIWAN 90118363 07/27/2001					
PG-PUB <input type="checkbox"/>		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO YUSO-131	
TITLE : Formation of electroplate solder on an organic circuit board for flip chip joints and board to board solder joints					
U.S. DEPT. OF COMM./PAT. & TM.-PTO-435L (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
		DRAWING	
		Sheets Drwg.	Figs. Drwg.
		Print Fig.	
		Application Examiner	
ISSUE FEE Amount Due Date Paid		PREPARED FOR ISSUE	
<input type="checkbox"/> TERMINAL DISCLAIMER		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.	

FILED WITH:

☐ DISK (CRF)

☐ CD-ROM
(Attached in pocket on right inside flap)